



## XZIF Double Sided-High Density Interconnect (XZIF DS-HD)

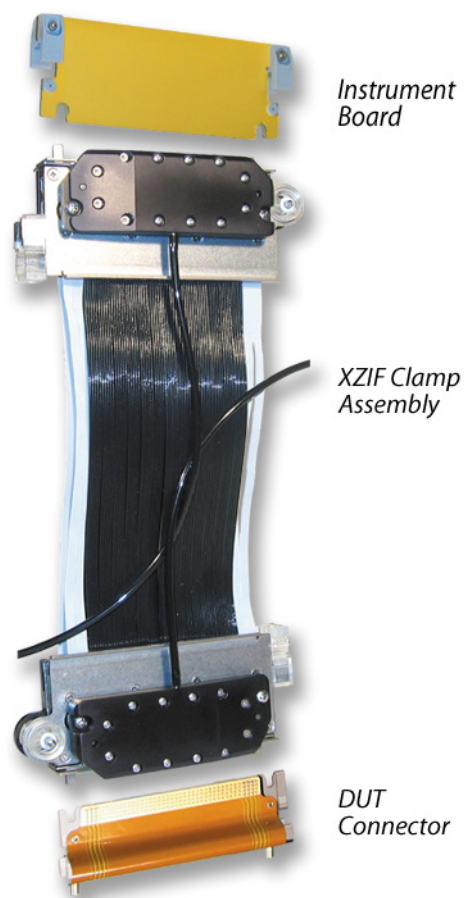
### Second Generation High Density Xandex Zero Insertion Force Interconnect (XZIF)

The Double Sided-High Density (DS-HD) XZIF interconnect is the second generation of XZIF development by Xandex. The DS-HD XZIF interconnect is designed to increase contact density and improve performance at a reduced cost per contact.

Compared to the first generation XZIF interconnect, the DS-HD electrical path is capable of significantly higher bandwidth and electrical performance with double the contact durability.

The modular XZIF interconnect is customizable to fit most test requirements. It is the optimal solution for volatile or non-volatile Memory test applications, SOC test applications and is ideal for dynamic high current delivery to the DUT.

And, by changing the direction of contact force from vertical (spring probe) to horizontal (clamp), the XZIF interconnect reduces compression force on the DUT test board by nearly 90%.



Second Generation XZIF DS-HD Interconnect Assembly

HISTC

### The XZIF DS-HD Interconnect Cycle

<p>1) The DUT connector approaches the clamp assembly.</p>	<p>2) The DUT connector engages the clamp and is aligned by guides on the clamp assembly.</p>	<p>3) The DUT connector is fully engaged in the clamp and compressed slightly in the clamp to ensure perfect alignment.</p>	<p>4) The clamp pneumatic cylinder is actuated, compressing the two sides of the clamp against the DUT connector with high force.</p>





# Narrow XZIF Double Sided-High Density Interconnect (XZIF DS-HDn)

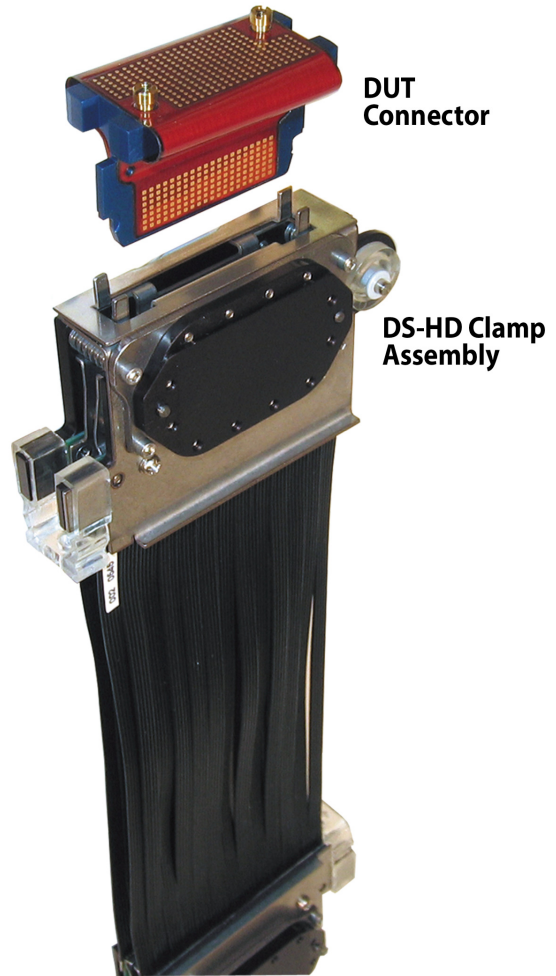
## High Density Xandex Zero Insertion Force Interconnect (XZIF) with Narrow Form Factor for High Density Memory Test Applications

The Narrow form factor Double Sided-High Density (DS-HD) XZIF interconnect is the second generation of XZIF development by Xandex for Memory Test. The DS-HDn XZIF interconnect is designed to increase contact density and improve performance at a reduced cost per contact.

Compared to the first generation XZIF flex interconnect, the DS-HDn XZIF utilizes interposer technology for higher channel density and superior DC contact resistance.

The modular XZIF interconnect is customizable to fit most test requirements. It is the optimal solution for volatile or non-volatile Memory test applications. The narrow form factor clamp is especially useful for smaller probe cards (300 + mm) or larger probe cards (440 + mm) with a large keep out area.

And, by changing the direction of contact force from vertical (spring probe) to horizontal (clamp), the XZIF interconnect reduces compression force on the DUT test board by nearly 90%.

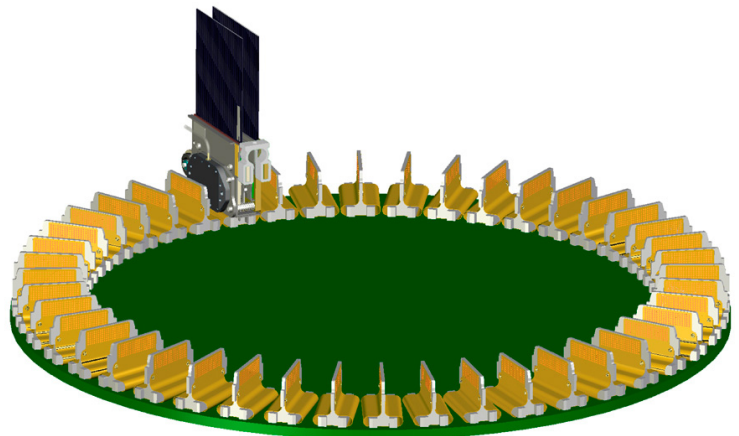


Second Generation XZIF DS-HDn Interconnect Assembly

**HISTC**

**HIGH DENSITY: >13,000 CONTACTS PER 440 MM PROBE CARD**

**SELF ALIGNING DUT CONNECTOR IS FIELD REPLACEABLE IN MINUTES WITH TWO SCREWS**





## Specifications:

<b>High Density</b>	
DS-HD contacts per assembly:	344
Contacts per linear inch:	>100
Contacts per 440mm probe card:	>13,000

<b>Low Insertion Force</b>	
Average Force per Assembly	5 lb [2.3 kg]
Maximum Force Per Assembly	<9 lb [4 kg]
13k contact XZIF	190 lb [86 kg]
13K contact spring pin (at 2.2 oz per pin)	1790 lb [812 kg]

<b>High Reliability</b>	
Multiple point contacts:	12 points per contact
Contact wipe:	Yes
High contact normal force:	> 50 grams
Typical contact resistance:	<10 mΩ
Maximum contact resistance:	< 50 mΩ contact resistance over 10k life

<b>High Performance</b>	
<i>Hi-Speed Configuration</i>	
Connectivity (per assembly):	132 coaxial channels and 56 utilities
-3 db Bandwidth:	> 4 GHz
Impedance control:	50 Ω ± 2.5 Ω @ 100 ps Tr <sub>10-90</sub>
Cross talk:	<2% FEXT/NEXT @ 500ps Tr <sub>10-90</sub>
<i>Hi-Power Configuration</i>	
Current capacity per assembly:	325 A
Total loop resistance:	< 2 mΩ
Total loop inductance:	< 500 pH

<b>Extended Life Contact</b>	
Minimum mate/de-mate cycles:	10k

<b>Serviceability</b>	
DUT board connector:	Self aligning DUT board connector is field replaceable in minutes

HISTORY

